

Amendment to the Specification

The Paragraph beginning at Page 1, line 1, is to be deleted.

At Page 1, Line 6, a new paragraph entitled "CROSS-REFERENCE TO RELATED APPLICATIONS" is to be added, just below the title, as follows:

IDC-A1,AMD

CROSS-REFERENCE TO RELATED APPLICATIONS

This is a Continuation Application of USSN 10/102,700 filed on March 22, 2002, now issued Patent No. 6,692,113.

The Paragraph beginning at Page 1, lines 11-15, is to be amended as follows:

IDC-A2,AMD

Various methods, systems and apparatus relating to the present invention are disclosed in the following co-pending applications filed by the applicant or assignee of the present invention:

09/575,141-6,428,133, 09/575,125-6,526,658, 09/575,108-6,795,215,
09/575,109.

The Paragraph beginning at Page 6, lines 24-31, is to be amended as follows:

IDC-A3,AMD

The "Memjet" printhead modules 11 are comprised of the "Memjet" chip 23, a fine pitch flex PCB 26 and two micro-moldings 28 and 34 sandwiching a mid-package film 35. Each module 11 forms a sealed unit with independent ink chambers 63 (Fig. 9) which feed the chip 23. The modules 11 plug directly onto a flexible elastomeric extrusion 15 which carries air, ink and fixative (see channels 49-55 in Fig. 15). The upper surface of the extrusion 15 has repeated patterns of holes 21 which align with ink inlets 32 (Fig. 3a) on the underside of each module 11. The extrusion 15 is bonded onto a flex PCB (flexible printed circuit board).

The Paragraph beginning at Page 8, lines 10-17, is to be amended as follows:

IDC-A4,AMD,M

The upper micro-molding 28 has a pair of alignment pins 29 passing through corresponding apertures in the mid-package film layer 35 to be received within corresponding recesses 66 in the lower micro-molding 34. This serves to align the components when they are bonded together. Once bonded together, the upper and lower micro-moldings form a tortuous ink and air path in the complete "Memjet" printhead module 11. In addition, an upper surface of the upper micro-molding 28 has a pair of

IDC-A4,AMD,M

opposed recesses 39 which serve as robot pick-up points for picking and placing the micro-molding.

The Paragraph beginning at Page 9, lines ¹⁹⁻²²~~24-28~~, is to be amended as follows:

yes
6/19/06

IDC-A5,AMD

The flex PCB 17 carries all data and power connections from the main PCB (not shown) to each "Memjet" printhead module 11. The flex PCB 17 has a series of gold plated, domed contacts 69 (Fig. 2) which interface with contact pads 41, 42 and 43 that are located together with section 44, -on the fine pitch flex PCB 26 of each "Memjet" printhead module 11.

The Paragraph beginning at Page 15, lines ⁴⁻⁹~~10-15~~, is to be amended as follows:

yes
6/19/06

IDC-A6,AMD

19. As shown in Fig. 14, a robot tool 58 grips the sides of the metal channel and pivots at pivot point against the underside face to effectively flex the channel apart by 200 to 300 microns. The forces applied are shown generally as force vectors F in Fig. 14. This allows the first "Memjet" printhead module to be robot picked and placed (relative to the first contact pads on the flex PCB 17 and ink extrusion holes) into the channel assembly. This is further facilitated by a recess 59 formed in the body of each module 11.